

7/9/1

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MANUFACTURE OF MULTILAYER TUBULAR CAPACITOR (English)

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4/9/1
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MANUFACTURE OF MULTILAYER TUBULAR CAPACITOR

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## **ABSTRACT**

PURPOSE: To provide a miniaturized device of large capacitance which is free from current leak and excellent in producibility by providing a sintered body of a dielectric material layer which is formed by an electrophoresis method by using dielectric material powder for particle in electrodeposition solution in at least a dielectric layer of a dielectric layer and a conductor layer.

CONSTITUTION: Two platinum rods are made a cathode and an anode, the platinum rods of electrode set are immersed in slurry of ceramic dielectric material powder, a voltage is applied between both electrodes and a first layer of a ceramic dielectric material layer 2 is formed. Thereafter, both electrodes are immersed in slurry of conductor material powder, a voltage is applied between both electrodes and a first layer of a conductor material layer 3 is formed. Similarly as above, ceramic dielectric material layers 2, 2..., and conductor material layers 3, 3... are formed one by one and a material lamination body is obtained. The material lamination body is baked, a platinum rod is drawn out and a ceramic element assembly chip of a tube 1 is obtained.